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Soundstation Engineer[™] Streamlines the Design of Active Noise Cancelling Headsets

New CAD tool unleashes power of HD-PA[®] compliant Soundcore R3 enabled audio devices by replacing passive components in filter tuning process with fingertip, drag and drop programming.

CES, Las Vegas, 7 January 2013 – Soundchip SA is pleased to announce the availability of Soundstation Engineer[™], an innovative computer-aided-design tool created to simplify the design of headsets with an active noise cancelling (ANC) feature.

The design and tuning of active noise cancellation and audio equalization filters in high performance ANC headsets has traditionally involved the selection and placement of many passive components around a conventional or so-called "noise cancelling" op-amp. However, to effectively balance the audio performance of a headset-in-design, this process can involve considerable iteration and rework, which can be time-consuming, costly and sometimes unsuccessful.

Soundstation Engineer has been developed to streamline the tuning process by providing headset designers with fingertip, drag and drop programming of active noise cancellation and audio equalization filters.

A Soundstation Engineer computer-aided-design station comprises the Soundstation Engineer software, complementary hardware incorporating a digitally programmable Soundcore R3 enabled audio device, and supporting cables.

Active noise cancellation and audio equalization filters are configured through a simple drag and drop approach and then immediately synchronized with complementary hardware, which is connected to the headset-in-design. The performance of candidate filters can be evaluated in real-time or measured and analyzed using other Soundchip or third party tools, including Mathworks Matlab[®].

Mark Donaldson, Soundchip's CEO said, "Developing active noise cancelling headsets with Soundstation Engineer and a Soundcore R3 enabled audio device is considerably faster and more reliable than methods proposed by competitors, which have proven problematic and costly for headset manufacturers."

Soundstation Engineer will be showcased to prospective customers in association with STMicroelectronics, an HD-PA[®] Partner, at the Consumer Electronics Show (CES) in Las Vegas, 8 - 11 January 2013.

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About Soundchip SA:

From its base in Switzerland Soundchip offers global customers access to a broad range of solutions in audio systems technology for sound at the ear. The company is the originator of the HD-PA Reference and is committed to providing customers with solutions that demonstrate the superior qualities of high definition sound in products designed for mobility and convenience. Soundchip licenses its solutions to leading brands involved in the design and manufacture of audio codecs, processors, sound transducers, multimedia systems and consumer products. Soundchip and HD-PA are registered trademarks of Soundchip SA. All rights reserved.

Further information on Soundchip can be found at www.soundchip.ch.

About HD-PA:

Consumers are adopting mobile entertainment, communications and gaming devices in ever increasing numbers with each new generation of device offering substantially improved power and performance. An aspect of end product that has remained relatively unchallenged during this period of growth is audio and in particular personal audio or audio delivered at the ear. As consumers search for a better sound experience on-the-go, an opportunity has emerged to demonstrate leadership in audio systems engineering and electroacoustics through intelligent innovation.

The High Definition Personal Audio[™] reference has been developed to encourage a step change in the performance and capabilities of personal audio devices. This change is achieved by applying innovative audio system technologies in concert with state-of-the-art processing and sensory silicon, including MEMS. Devices that comply with the HD-PA[®] reference meet an ambitious standard of performance and offer their users enhanced sound quality, comfort and convenience in a manner that is resilient to environmental factors, including noise.